



#8/60E

Docket No.: M1071.1453/P1453  
(PATENT)

7/3/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
Haruhiko Ikeda

Application No.: 09/927,053

Group Art Unit: 1733

Filed: August 9, 2001

Examiner: John T. Haran

For: METHOD OF BONDING A  
CONDUCTIVE ADHESIVE AND AN  
ELECTRODE, AND A BONDED  
ELECTRODE OBTAINED THEREBY

**RECEIVED**  
JUL 01 2003  
TC 1700

RESPONSE TO RESTRICTION REQUIREMENT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

In response to the Restriction Requirement set forth in the Office Action mailed June 5, 2003, Applicant hereby provisionally elects claims 19-27, drawn to a bonded structure, for continued examination, without traverse.

Applicant reserves the right to file one or more divisional applications directed to the subject matter of the non-elected claims.

Consideration and allowance of the application is respectfully solicited.

Dated: June 30, 2003

Respectfully submitted,

By

Richard LaCava

Registration No.: 41,135  
DICKSTEIN SHAPIRO MORIN &  
OSHINSKY LLP  
1177 Avenue of the Americas  
41st Floor  
New York, New York 10036-2714  
(212) 835-1400  
Attorneys for Applicant